

Error Codes Reported By XDC

Amit Mookerjee

Platform Support Group

ABSTRACT

The eXpress DSP Components (XDC) is a standard for delivering named, versioned, reusable software components, called "packages". XDC includes tools and standards for API development, static configuration, and packaging. This document summarizes the error status messages reported by the XDC tools.

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1 Introduction

The eXpress DSP Components (XDC) is a standard for delivering named, versioned, reusable software components, called "packages". XDC includes tools and standards for API development, static configuration, and packaging.

XDC provides tools to configure XDC packages and integrate them into the project. Configuration scripts specify package contents, options and settings. When processed, the configuration script generates output files that are linked into the project with the user application. The xs executable is used to run the XDC scripts in a command window.

2 XDC Error Messages

The XDC tools emit messages with an error code whenever errors are encountered during execution.

The following sub-sections summarize the errors defined in the XDC package and in the XDC configuration and build packages.

These error messages should not be confused with the XDC run-time error manager module, for raising and handling errors within your program.



2.1 Errors Defined in the xdc Package

This section lists the errors defined in the ${\tt xdc}$ package itself.

Error	Description	
xdc.PACKAGE_NOT_FOUND	This error is reported when a specified package is not found. This may happen for the following reasons:	
	The XDCPATH environment variable is not set up properly. Ensure that the package path is included in the XDCPATH environment variable.	
	 The package has not been built by the XDC tool even though the physical package directory may be present along XDCPATH. 	
xdc.FILE_NOT_FOUND	This error is reported when a specified file is not found. Ensure that the environment variable XDCPATH is set correctly.	
xdc.MODULE_NOT_FOUND	This error is reported when a specified module is not found. Ensure that the package path is included in the XDCPATH environment variable. Also ensure that the module name is qualified with the package name. For example, to refer to the module Engine in the package ti.sdo.ce, specify the module name as ti.sdo.ce.Engine.	
xdc.TOOL_USAGE_ERROR	This error indicates that the expected command line arguments were not passed to the xs tool. xs tool usage is : xs [-m] <name> <args></args></name>	
xdc.MODULE_UNDEFINED_MAIN_FUNCTION	This error is reported when the xs tool is passed a module that does not define a main function. Ensure that the meta-domain implementation of the module has a main function.	
xdc.SPEC_FILE_ERROR	This error is reported when there is a parsing error in a specification file. Check the specification file for syntax errors.	
xdc.DEPRECATED_FUNCTION	This error is reported whenever a deprecated function is called.	

2.2 Errors Defined in the xdc.bld Package

The following error messages are defined in the xdc.bld package.

Error	Description		
xdc.bld.PARAMETER_MISMATCH	This error is reported whenever incorrect parameters are passed to a module function. Ensure that the parameters passed to the function have the correct type. This error is reported by the following modules:		
	-xdc.bld.PackageContents:addLibrary, addAssembly, addExecutable, addRelease, addRepository, addScript		
	-xdc.bld.BuildEnvironment:usePlatform, isInTargetsArray		
xdc.bld.PACKAGE_NOT_BUILT	This error is reported if a consumer tries to use a package that has not been built. Ensure that the required package has been built by the XDC tool. This error is reported by the getReleaseDescs method in the xdc.bld.BuildEnvironment module.		
xdc.bld.TARGET_CONFIG_ERROR	This error is reported whenever there is an error in the target configuration file. Check the configuration script for errors.		
xdc.bld.ROOTDIR_NOT_SET	This error is reported when the rootDir property for a target has not been set in the target configuration script. Ensure that this property is set correctly in the configuration script.		
xdc.bld.INVALID_PACKAGE	This error is reported when a consumer tries to use a corrupted package. Try rebuilding the package causing the problem. This error is reported by the getReleaseDescs method in the xdc.bld.BuildEnvironment module.		



xdc.bld.INVALID_TARGET	This error is reported when a package is built for an unspecified target. Ensure that the correct targets are mentioned in the package's build script. This error is reported by the addLibrary, addExecutable, and addAssembly methods in the xdc.bld.PackageContents module.		
xdc.bld.EXECUTABLE_EXISTS	This error is reported when a package's build script specifies multiple executables with the same name. Ensure that the names of the executables to be built are unique. This error is reported by the addExecutable method in the xdc.bld.PackageContents module.		
xdc.bld.LIBRARY_EXISTS	This error is reported when a package's build script specifies multiple libraries with the same name. Ensure that the names of the libraries to be built are unique. This error is reported by the addLibrary method in the xdc.bld.PackageContents module.		
xdc.bld.INCORRECT_PACKAGE_NAME	This error is reported whenever a package name does not match the directory name. Package names should match the directory layout. For example the package ti.sdo.ce.osal should be created in the directory ti\sdo\ce\osal.		
xdc.bld.CREATE_DIR_ERROR	This error is reported whenever there is an error in creating package directories. This may be related to issues with the host file system. Check whether directories can be created manually in the package sub-directory.		
xdc.bld.REPOSITORY_EXISTS	This error is reported whenever a package's build script specifies multiple repositories with the same name. Ensure that the names of the repositories specified in the build script are unique. This error is reported by the addRepository method in the xdc.bld.PackageContents module.		
xdc.bld.RELEASE_EXISTS	This error is reported whenever a package's build script specifies multiple releases with the same name. Ensure that the names of the releases specified in the build script are unique. This error is reported by the addRelease method in the xdc.bld.PackageContents module.		
xdc.bld.INVALID_RELEASE_PREFIX	This error is reported whenever a release prefix is specified by its absolute path in the package's build script. The release prefix must be relative to the package's base directory. This error is reported by the addRelease method in the xdc.bld.PackageContents module.		
xdc.bld.INVALID_RELEASE_NAME	This error is reported whenever a release name is specified by its absolute path in the package's build script. The release name must be relative to the package's base directory. This error is reported by the addRelease method in the xdc.bld.PackageContents module.		
xdc.bld.SCRIPT_EXISTS	This error is reported whenever a package's build script specifies multiple user scripts with the same name. Ensure that the names of the user scripts are unique. This error is reported by the addScript method in the xdc.bld.PackageContents module.		

2.3 Errors Defined in the xdc.cfg Package

The following error is defined by the xdc.cfg package.

Error	Description	
xdc.cfg.CONFIG_ERROR	This is a general error reported when the program configuration fails. This error is caused by one or more configuration errors. The list of those specific errors precedes this error.	

3 References

- XDC Consumer User's Guide (SPRUEX4)
- XDC Getting Started Guide (XDC_INSTALL_DIR/doc/XDC_Getting_Started_Guide.pdf)

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